

Fast-curing mCD adhesives

Heat pulse process makes for curing in seconds

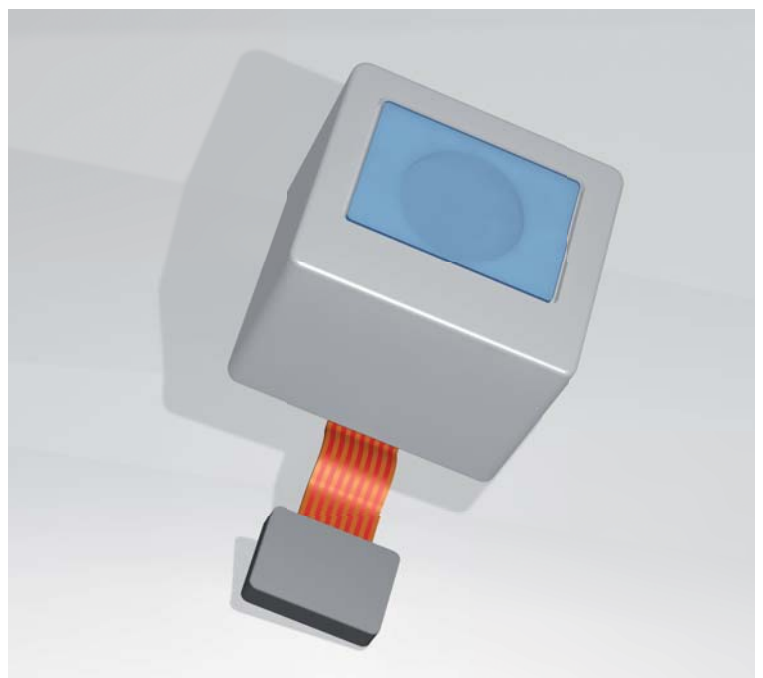
Application areas	Advantages	Properties
<ul style="list-style-type: none">▪ Compact camera modules (CCM)▪ RFID and smart labels▪ Electronic assembly▪ Areas with demanding requirements (short cycle times, fast processes)▪ Automotive and electronics industry	<ul style="list-style-type: none">▪ Ideal for processes with high throughput▪ Highest reliability▪ Cycle times of milliseconds▪ Can be used in connection with temperature-sensitive materials	<ul style="list-style-type: none">▪ Modified epoxy resins▪ Low curing temperature, below +90 °C▪ Available as NCA, ACA, ICA, die attach and DELO-DUALBOND adhesives▪ Excellent adhesion to standard materials (PVC, PPA, PBT, FR4)▪ Improved flow behavior

Unique: Heat pulse process

- Heating of the first component to +250 °C to +350 °C
- Positioning of the second component to which the mCD adhesive has been applied in advance

Advantage: Extremely fast curing

For compact camera modules widely differing elements are bonded, such as the housing to the PCB



	DELO-DUALBOND AD340	DELO-MONOPOX NU355	DELO-MONOPOX NU VE80028
Color	Beige ¹	Beige	Beige
Viscosity [mPas]	12,000	34,000	26,000
Curing temperature [°C]	Min.	+80	+80
	Max.	+150	+150
Light-curing step	Prefixing 5 – 10 s (320 – 400 nm)	–	–
Heat-curing step	Convection oven	15 min @ +100 °C	30 min @ +80 °C
	By thermode	–	5 s @ +150 °C
Compression shear strength [MPa] PC/PC	35	6	New product type; data on request
Tensile strength [MPa]	11	42	
Elongation at tear [%]	4	4.5	
Young's modulus [MPa]	400	1,700	
Glass transition temperature [°C]	75	72	
Shore hardness	D 52	D 76	
Storage life	6 months / –18 °C	6 months / –18 °C	3 months / –18 °C
Properties	<ul style="list-style-type: none"> ▪ Prefixing with UVA light ▪ Fast fixing ▪ Low-temperature curing 	<ul style="list-style-type: none"> ▪ Low-temperature curing ▪ Very fast curing 	<ul style="list-style-type: none"> ▪ For higher layer thicknesses ▪ Low-temperature curing

¹ Black product available on request

Application example: Bonding of compact camera module

